

Title (en)

EPOXY COMPOUND HAVING ALKOXYSILYL GROUP, COMPOSITION AND HARDENED MATERIAL COMPRISING SAME, USE FOR SAME, AND PRODUCTION METHOD FOR EPOXY COMPOUND HAVING ALKOXYSILYL GROUP

Title (de)

EPOXIDVERBINDUNG MIT EINER ALKOXYSILYLGRUPPE, ZUSAMMENSETZUNG UND GEHÄRTETES MATERIAL DAMIT, VERWENDUNG DAVON UND VERFAHREN ZUR HERSTELLUNG EINER EPOXIDVERBINDUNG MIT EINER ALKOXYSILYLGRUPPE

Title (fr)

COMPOSÉ ÉPOXY PRÉSENTANT UN GROUPE ALCOXYSILYLE, COMPOSITION ET MATÉRIAU DURCI LE COMPRENANT, SON UTILISATION ET PROCÉDÉ DE PRÉPARATION DU COMPOSÉ ÉPOXY PRÉSENTANT UN GROUPE ALCOXYSILYLE

Publication

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Application

EP 13772355 A 20130402

Priority

- KR 20120034070 A 20120402
- KR 2013002730 W 20130402

Abstract (en)

[origin: EP2835373A1] The present invention relates to: an alkoxyethyl-based epoxy compound which does not require a separate silane coupling agent and exhibits outstanding heat resistance, and more specifically a low coefficient of thermal expansion (CTE) and a high glass transition temperature in a synergistic effect in a composite material; a composition and a cured article comprising same; a use for same; and a production method for an epoxy compound having an alkoxyethyl group. Accordingly, the present invention provides: an epoxy compound having an epoxy group and an alkoxyethyl group; and a composition comprising the epoxy compound together with a curing agent, a filler and/or a reaction catalyst or the like, and various uses for same including in a cured article and electronic components. According to the present invention, the novel epoxy composition comprising the epoxy compound having the alkoxyethyl group exhibits improved heat resistance, which is to say an effect whereby the CTE of the epoxy composite is reduced and whereby the glass transition temperature is elevated or a glass transition temperature is not exhibited (referred to hereinbelow as "T_g less"), because of chemical bond formation due to a chemical reaction of the alkoxyethyl group and the filler (fibres and/or particles) and a chemical reaction between alkoxyethyl groups, in the composite material and/or the cured article. Moreover, the cured article comprising the epoxy compound having the alkoxyethyl group according to the present invention exhibits outstanding flame retardancy due to the inclusion of the alkoxyethyl group.

IPC 8 full level

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Citation (search report)

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DOCDB simple family (application)

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